



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D

** : Required Field*


Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2016-06-23
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Rossana Bonaccorso	Representative Title	ADG MD Champion
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard
Legal Statement	<p>Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.</p>		

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
TN4015H-6G-TR	7AD1*406HMM1	A	SHENZHEN B/E	2016-06-23
	Amount	UoM	Unit type	ST ECOPACK Grade
	1380.00	mg	Each	ECOPACK2

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	245	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
SIP	10.2-10.5-1.27	3	GULL WING	
Comment	D2PAK CLIP			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	false
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	true
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
5 - Product(s) is obsolete, no information is available	false
6 - Product(s) is unknown, no information is available	false
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)
7c-I	Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound

QueryList : REACH-20th June 2016				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	7AD1*406HMM1									
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)				
Die	Other inorganic materials	13.510	mg	supplier	die	Silicon (Si)	7440-21-3		11.711	mg	866849	8487				
				supplier	metallization	Nickel (Ni)	7440-02-0		0.235	mg	17393	170				
				supplier	metallization	Gold (Au)	7440-57-5		0.044	mg	3258	32				
				supplier	Passivation	Silicon Oxide	7631-86-9		0.067	mg	4959	49				
				supplier	back side metallization	Gold (Au)	7440-57-5		0.015	mg	1110	11				
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.318	mg	23536	230				
				supplier	glass coating	Glass : Aluminium Oxide	1344-28-1		0.094	mg	6957	68				
				JIG - R	glass coating	Lead-Borate Glass	65997-18-4	7c-I-Electrical and e	1.026	mg	75938	743				
				Leadframe	Copper & its alloys	900.740	mg	supplier	alloy	Copper (Cu)	7440-50-8		899.839	mg	999000	652057
								supplier	alloy	CopperPhosphorous (CuP)	12517-41-8		0.901	mg	1000	653
JIG - R	solder	Lead (Pb)	7439-92-1					7a-Lead in high me	11.470	mg	925000	8312				
Soft solder	Solder	12.400	mg	supplier	solder	Silver (Ag)	7440-22-4		0.620	mg	50000	449				
				supplier	solder	Tin (Sn)	7440-31-5		0.310	mg	25000	225				
				supplier	mold compound	Silica, vitreous	60676-86-0		315.712	mg	759999	228777				
Encapsulation	Other Organic Materials	415.411	mg	supplier	mold compound	Epoxy Cresol Novolak	29690-82-2		42.372	mg	102000	30704				
				supplier	mold compound	Phenol resin	9003-35-4		24.925	mg	60002	18062				
				supplier	mold compound	Others	Proprietary		20.771	mg	50001	15051				
				supplier	mold compound	Metal hydroxide	21645-51-2		8.308	mg	19999	6020				
				supplier	mold compound	Carbon black	1333-86-4		3.323	mg	7999	2408				
Connections coating	Solder	6.314	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		6.314	mg	1000000	4575				
Clip	Copper & its alloys	31.625	mg	supplier	alloy	Copper (Cu)	7440-50-8		31.625	mg	1000000	22917				